



Prof. Tadatomo Suga

(Meisei University, Japan)



Prof. Tadatomo Suga joined the Max Planck Institute for Metal Research in 1979 and received his PhD in Materials Science from the University of Stuttgart in 1983. He has been a professor at the University of Tokyo since 1993. He has also served as director of the Interconnect Ecodesign Research Group at the National Institute of Materials Science (NIMS), member of the Japan Council of Science and Technology, chairman of the IEEE CPMT Society Japan Chapter, and president of the Japan Institute for Electronic Packaging (JIEP).

Prof. Suga's research has significantly advanced the field of materials science and engineering. His focus on microsystem integration and packaging and the development of interconnect technology, particularly room-temperature bonding technology, "surface activated bonding," has led to groundbreaking discoveries and innovations in 3D and heterogeneous integration. he retired from the University of Tokyo to become Professor Emeritus and subsequently joined Meisei University to continue his research work.